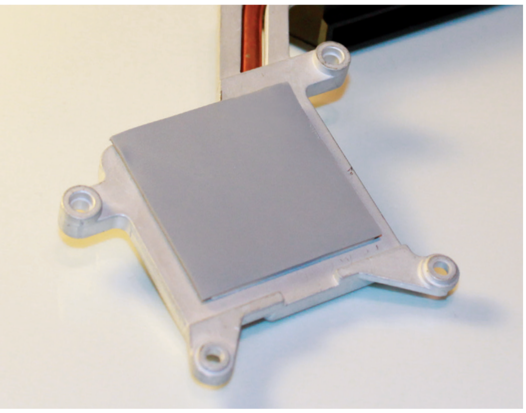
TG-X2

Ultra Soft Thermal Conductive Pad

in partnership with



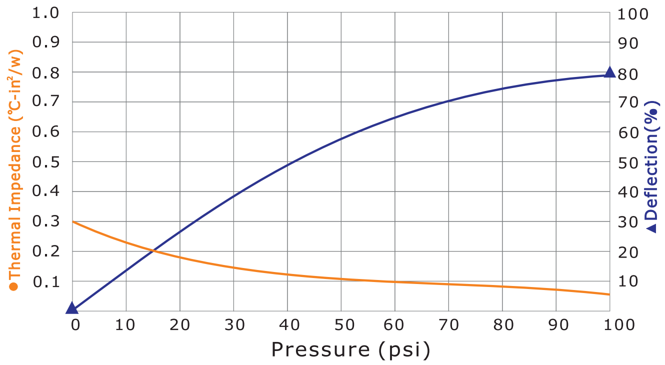
Features

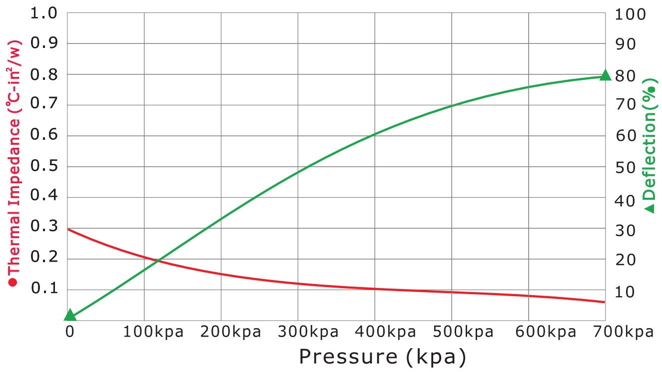
Superior thermal conductivity
Highly compressible
Naturally tacky
Low Shore 00 hardness
Low oil bleed
Electrically insulating

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



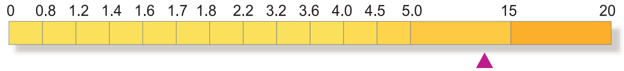


Properties

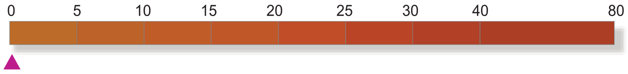
⬢ REACH Compliant

⬢ RoHS Compliant

Thermal Conductivity: 12 W/m.k
(W / m.k - Z Axis)



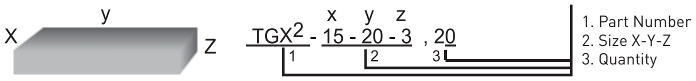
Hardness: 0 (Shore 00)
(Shore 00)



Testing sample thickness: 1.5mm

In the thermal resistance vs pressure vs deflection charts TG-X2 provides low thermal impedance.
As the pressure increases the thermal impedance decreases. TG-X2 provides good compliance and softness.

Property	TG-X2	Unit	Test Method
Colour	Grey	-	Visual
Operating Temperature Range	-45 to +200	˚C	-
Density	3.4	-	-
Thermal Conductivity	12	W/m.k	ASTM D5470
Hardness	0	Shore 00	ASTM D2240
t=1mm Thermal Impedance @ 10psi	0.11	˚c in^2/W	ASTM D5470
t=1mm Thermal Impedance @ 50psi	0.09	˚c in^2/W	ASTM D5470
t=1mm Thermal Impedance @ 10psi	0.04	˚c in^2/W	ASTM D5470
t=1mm Percent Deflection @ 10psi	24	%	-
t=1mm Percent Deflection @ 50psi	63	%	-
t=1mm Percent Deflection @ 100psi	81	%	-
Volume Resistance	$>10^{10}$	Ohm-cm	ASTM D257
Total Mass Loss	<0.4	%	ASTM E595
Flame Rating	V-0	-	UL 94
Breakdown Voltage	13	kV	ASTM D149



1. Part Number
2. Size X-Y-Z
3. Quantity